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# ASSP

## Single Serial Input PLL Frequency Synthesizer On-chip 2.0 GHz Prescaler

### MB15E05SR

#### ■ DESCRIPTION

The Fujitsu Semiconductor MB15E05SR is a serial input Phase Locked Loop (PLL) frequency synthesizer with a 2.0 GHz prescaler. The 2.0 GHz prescaler has a dual modulus division ratio of 64/65 or 128/129 enabling pulse swallowing operation.

The supply voltage range is between 2.7 V and 5.0 V. A refined charge pump supplies well-balanced output currents of 1.0 mA and 4.0 mA. The charge pump current is selectable by serial data.

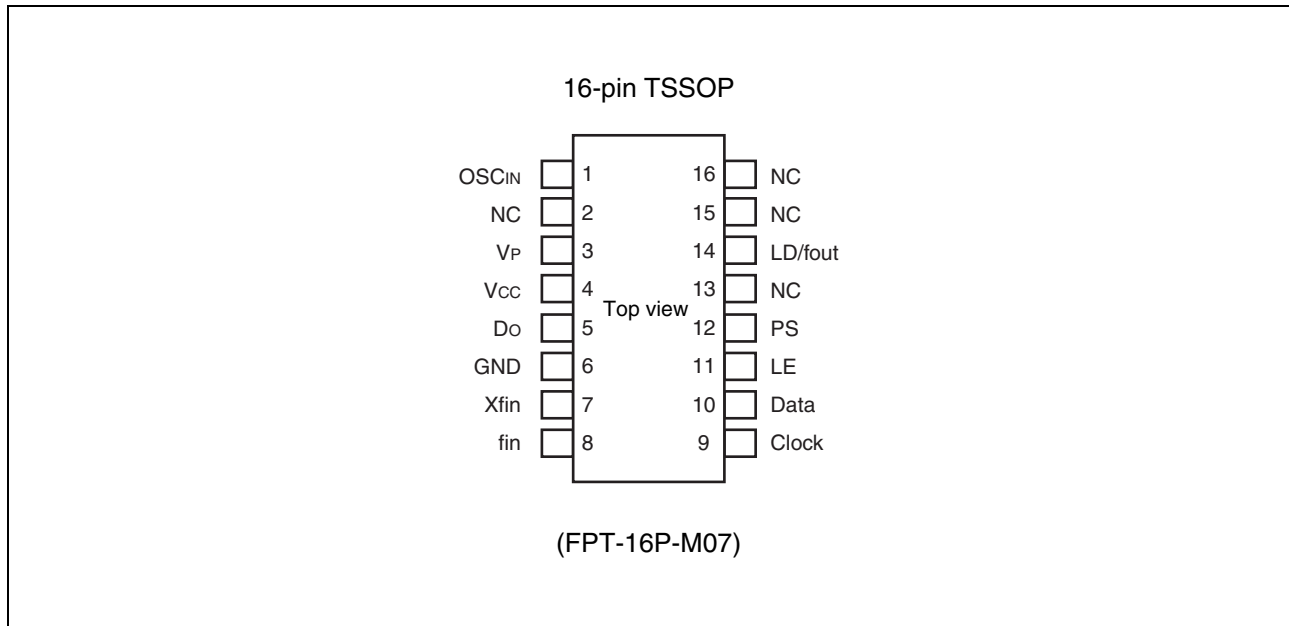
The phase noise of MB15E05SR was drastically improved comparing with the former single PLL, MB15E05SL. The data format of serial data and the pin assignments except for  $\phi P$ ,  $\phi R$  and OSCout pins are same as the former one, so it is easy to replace the former one.

MB15E05SR is ideally suited for the base station of GSM (Global System for Mobile Communications) and PCS.

#### ■ FEATURES

- High frequency operation: 2.0 GHz Max
- Low power supply voltage:  $V_{CC} = 2.7 \text{ V to } 5.0 \text{ V}$
- Ultra Low power supply current:  $I_{CC} = 7.0 \text{ mA Typ}$  ( $V_{CC} = V_p = 3.75 \text{ V}$ ,  $T_a = +25^\circ\text{C}$ , in locking state)
- Direct power saving function: Power supply current in power saving mode  
Typ 0.1  $\mu\text{A}$  ( $V_{CC} = V_p = 3.75 \text{ V}$ ,  $T_a = +25^\circ\text{C}$ )
- Dual modulus prescaler: 64/65 or 128/129
- Serial input 14-bit programmable reference divider:  $R = 3 \text{ to } 16,383$
- Serial input programmable divider consisting of:
  - Binary 7-bit swallow counter: 0 to 127
  - Binary 11-bit programmable counter: 3 to 2,047
- Software selectable charge pump current
- On-chip phase control for phase comparator
- Built-in digital locking detector circuit to detect PLL locking and unlocking.
- Operating temperature:  $T_a = -40^\circ\text{C to } +85^\circ\text{C}$

## ■ PIN ASSIGNMENTS

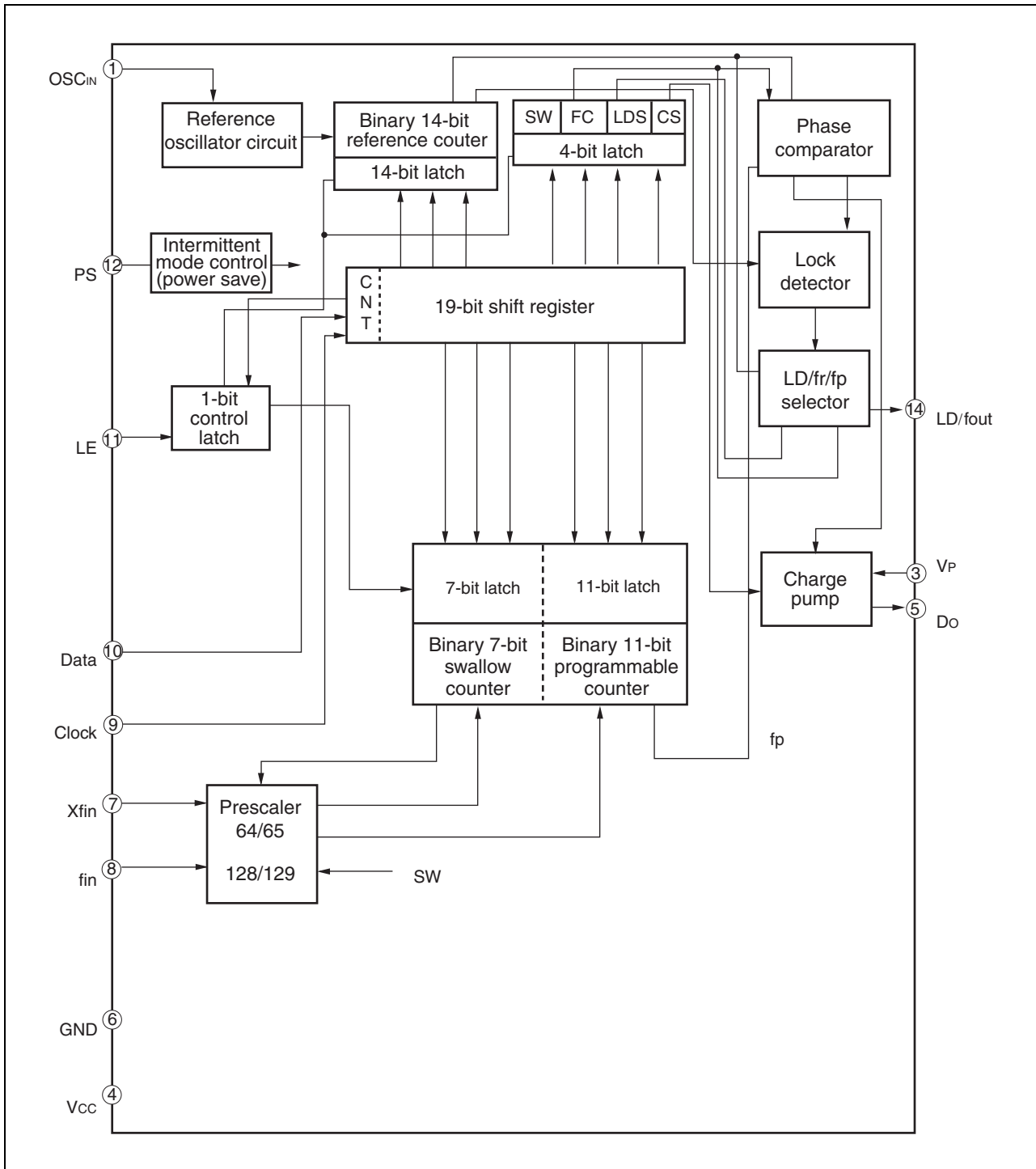


## ■ PIN DESCRIPTIONS

Pin no. TSSOP	Pin name	I/O	Descriptions
1	OSC <sub>IN</sub>	I	Programmable reference divider input. Connection to a TCXO.
2	NC	–	No connection.
3	V <sub>P</sub>	–	Power supply voltage input for the charge pump.
4	V <sub>CC</sub>	–	Power supply voltage input.
5	D <sub>o</sub>	O	Charge pump output. Phase of the charge pump can be selected via programming of the FC bit.
6	GND	–	Ground.
7	Xfin	I	Prescaler complementary input, which should be grounded via a capacitor.
8	fin	I	Prescaler input. Connection to an external VCO should be done via AC coupling.
9	Clock	I	Clock input for the 19-bit shift register. Data is shifted into the shift register on the rising edge of the clock. (Open is prohibited.)
10	Data	I	Serial data input using binary code. The last bit of the data is a control bit. (Open is prohibited.)
11	LE	I	Load enable signal input. (Open is prohibited.) When LE is set high, the data in the shift register is transferred to a latch according to the control bit in the serial data.
12	PS	I	Power saving mode control. This pin must be set at “L” at Power-ON. (Open is prohibited.) PS = “H”; Normal mode PS = “L”; Power saving mode
13	NC	–	No connection.
14	LD/fout	O	Lock detect signal output (LD)/phase comparator monitoring output (fout). The output signal is selected via programming of the LDS bit. LDS = “H”; outputs fout (fr/fp monitoring output) LDS = “L”; outputs LD (“H” at locking, “L” at unlocking.)
15	NC	–	No connection.
16	NC	–	No connection.

# MB15E05SR

## ■ BLOCK DIAGRAM



## ■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condi- tion	Rating		Unit	Remark
			Min	Max		
Power supply voltage	V <sub>CC</sub>	–	–0.5	5.5	V	
	V <sub>P</sub>	–	V <sub>CC</sub>	6.0	V	
Input voltage	V <sub>I</sub>	–	–0.5	V <sub>CC</sub> +0.5	V	
Output voltage	V <sub>O</sub>	Except Do	GND	V <sub>CC</sub>	V	
	V <sub>O</sub>	Do	GND	V <sub>P</sub>	V	
Storage temperature	T <sub>stg</sub>	–	–55	+125	°C	

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

## ■ RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Value			Unit	Remark
		Min	Typ	Max		
Power supply voltage	V <sub>CC</sub>	2.7	3.75	5.0	V	
	V <sub>P</sub>	V <sub>CC</sub>	–	5.5	V	
Input voltage	V <sub>I</sub>	GND	–	V <sub>CC</sub>	V	
Operating temperature	T <sub>a</sub>	–40	–	+85	°C	

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

# MB15E05SR

## ■ ELECTRICAL CHARACTERISTICS

( $V_{CC} = 2.7\text{ V to }5.0\text{ V}$ ,  $T_a = -40\text{ }^\circ\text{C to }+85\text{ }^\circ\text{C}$ )

Parameter	Symbol	Condition	Value			Unit		
			Min	Typ	Max			
Power supply current*1	$I_{CC}$	$f_{in} = 2000\text{ MHz}$ , $V_{CC} = V_P = 3.75\text{ V}$	–	7.0	–	mA		
Power saving current	$I_{PS}$	PS = "L"	–	$0.1^{*2}$	20	$\mu\text{A}$		
Operating frequency	$f_{in}$	$f_{IN}$	–	300	2000	MHz		
	OSC <sub>IN</sub>	$f_{osc}$	–	3	40	MHz		
Input sensitivity	$f_{in}^{*3}$	$P_{fin}$	50 $\Omega$ system (Refer to the measurement circuit.)	–15	–	+2	dBm	
	OSC <sub>IN</sub> <sup>*3</sup>	$V_{OSC}$	–	0.5	–	$V_{CC}$	Vp-p	
"H" level input voltage	Data, Clock, LE, PS	$V_{IH}$	–	$V_{CC} \times 0.7$	–	V		
"L" level input voltage		$V_{IL}$	–	–	$V_{CC} \times 0.3$			
"H" level input current	Data, Clock, LE, PS	$I_{IH}^{*4}$	–	–1.0	–	+1.0	$\mu\text{A}$	
"L" level input current		$I_{IL}^{*4}$	–	–1.0	–	+1.0		
"H" level input current	OSC <sub>IN</sub>	$I_{IH}$	–	0	–	+100	$\mu\text{A}$	
"L" level input current		$I_{IL}^{*4}$	–	–100	–	0		
"H" level output voltage	LD/fout	$V_{OH}$	$V_{CC} = V_P = 3.75\text{ V}$ , $I_{OH} = -1\text{ mA}$	$V_{CC} - 0.4$	–	–	V	
"L" level output voltage		$V_{OL}$	$V_{CC} = V_P = 3.75\text{ V}$ , $I_{OL} = 1\text{ mA}$	–	–	0.4		
"H" level output voltage	Do	$V_{DOH}$	$V_{CC} = V_P = 3.75\text{ V}$ , $I_{DOH} = -0.5\text{ mA}$	$V_P - 0.4$	–	–	V	
"L" level output voltage		$V_{DOL}$	$V_{CC} = V_P = 3.75\text{ V}$ , $I_{DOL} = 0.5\text{ mA}$	–	–	0.4		
High impedance cutoff current	Do	$I_{OFF}$	$V_{CC} = V_P = 3.75\text{ V}$ , $V_{OFF} = 0.5\text{ V to }V_P - 0.5\text{ V}$	–	–	2.5	nA	
"H" level output current	LD/fout	$I_{OH}$	$V_{CC} = V_P = 3.75\text{ V}$	–	–	–1.0	mA	
"L" level output current		$I_{OL}$	$V_{CC} = V_P = 3.75\text{ V}$	1.0	–	–		
"H" level output current	Do	$I_{DOH}^{*4}$	$V_{CC} = 3.75\text{ V}$ , $V_P = 3.75\text{ V}$ , $V_{DO} = V_P/2$ , $T_a = +25^\circ\text{C}$	CS bit = "1"	–	–4.0	–	mA
				CS bit = "0"	–	–1.0	–	
		$I_{DOL}$		CS bit = "1"	–	4.0	–	
CS bit = "0"				–	1.0	–		
Charge pump current rate	$I_{DOL}/I_{DOH}$	$I_{DOMT}^{*5}$	$V_{DO} = V_P/2$	–	5	–	%	
	vs $V_{DO}$	$I_{DOVD}^{*6}$	$0.5\text{ V} \leq V_{DO} \leq V_P - 0.7\text{ V}$	–	10	–	%	
	vs $T_a$	$I_{DOTA}^{*7}$	$-40^\circ\text{C} \leq T_a \leq +85^\circ\text{C}$ , $V_{DO} = V_P/2$	–	3	–	%	

\*1: Conditions;  $f_{osc} = 13\text{ MHz}$ ,  $V_{OSC} = 1.2\text{ V}_{PP}$ ,  $T_a = +25^\circ\text{C}$ , in locking state.

\*2:  $V_{CC} = V_P = 3.75\text{ V}$ ,  $f_{osc} = 13\text{ MHz}$ ,  $V_{OSC} = 1.2\text{ V}_{PP}$ ,  $T_a = +25^\circ\text{C}$ , in power saving mode

\*3: AC coupling. 1000 pF capacitor is connected under the condition of min. operating frequency.

\*4: The symbol "–" (minus) means direction of current flow.

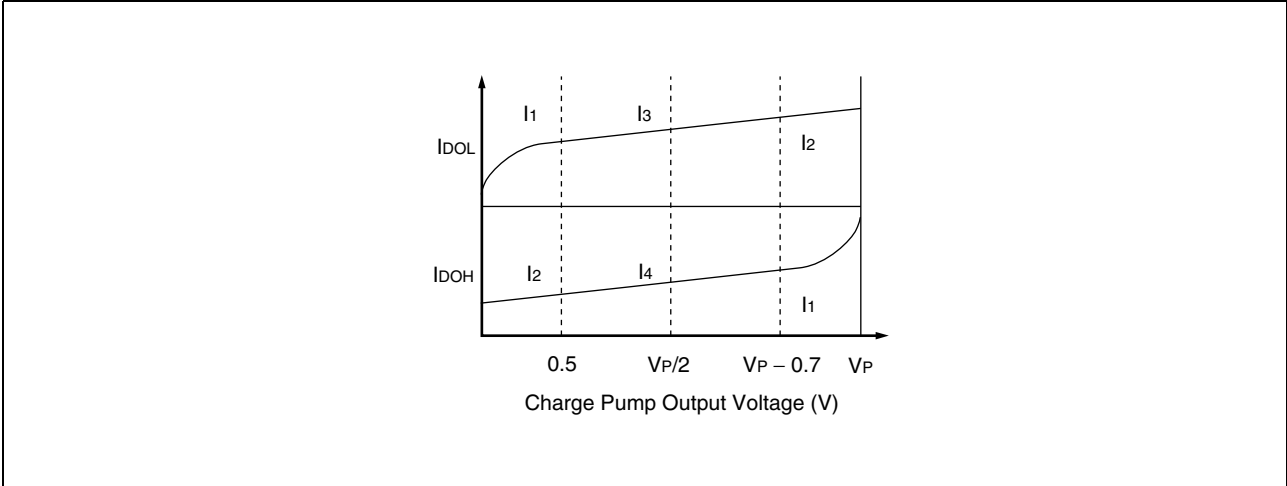
\*5:  $V_{CC} = V_P = 3.75\text{ V}$ ,  $T_a = +25^\circ\text{C}$  ( $(|I_3| - |I_4|) / [(|I_3| + |I_4|) / 2] \times 100(\%)$ )

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\*6:  $V_{CC} = V_P = 3.75 \text{ V}$ ,  $T_a = +25^\circ\text{C}$   $[(|I_2| - |I_1|) / 2] / [(|I_1| + |I_2|) / 2] \times 100(\%)$  (Applied to each  $I_{DOL}$ ,  $I_{DOH}$ )

\*7:  $V_{CC} = V_P = 3.75 \text{ V}$ ,  $V_{DO} = V_P/2$   $(|I_{DO(+85^\circ\text{C})}| - |I_{DO(-40^\circ\text{C})}|) / 2 / (|I_{DO(+85^\circ\text{C})}| + |I_{DO(-40^\circ\text{C})}|) / 2 \times 100(\%)$   
 (Applied to each  $I_{DOL}$ ,  $I_{DOH}$ )



## ■ FUNCTIONAL DESCRIPTION

### 1. Pulse Swallow Function

The divide ratio can be calculated using the following equation:

$$f_{vco} = [(P \times N) + A] \times f_{osc} \div R \quad (A < N)$$

$f_{vco}$  : Output frequency of external voltage controlled oscillator (VCO)

$N$  : Preset divide ratio of binary 11-bit programmable counter (3 to 2,047)

$A$  : Preset divide ratio of binary 7-bit swallow counter ( $0 \leq A \leq 127$ )

$f_{osc}$  : Output frequency of the reference frequency oscillator

$R$  : Preset divide ratio of binary 14-bit programmable reference counter (3 to 16,383)

$P$  : Preset divide ratio of modulus prescaler (64 or 128)

### 2. Serial Data Input

Serial data is processed using the Data, Clock, and LE pins. Serial data controls the programmable reference divider and the programmable divider separately.

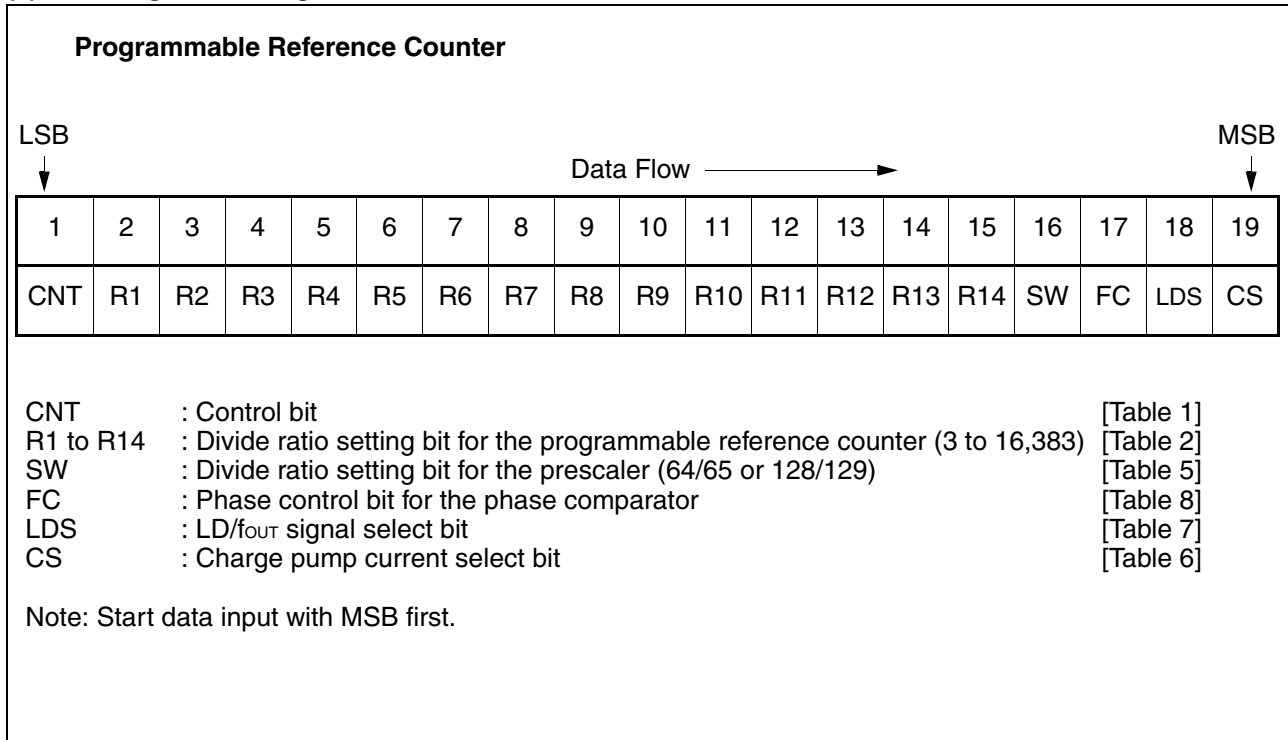
Binary serial data is entered through the Data pin.

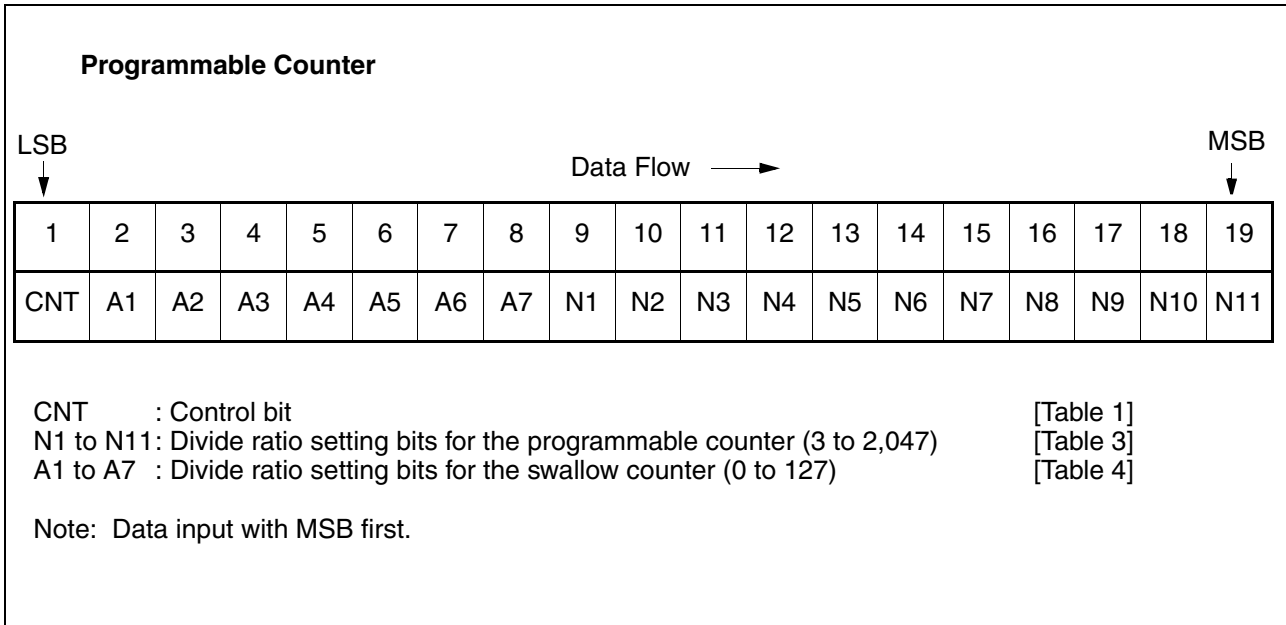
One bit of data is shifted into the shift register on the rising edge of the Clock. When the LE signal pin is taken high, stored data is latched according to the control bit data as follows:

**Table 1. Control Bit**

Control bit (CNT)	Destination of serial data
H	For the programmable reference divider
L	For the programmable divider

#### (1) Shift Register Configuration





**Table 2. Binary 14-bit Programmable Reference Counter Data Setting**

Divide ratio(R)	R14	R13	R12	R11	R10	R9	R8	R7	R6	R5	R4	R3	R2	R1
3	0	0	0	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	0	0	0	1	0	0
·	·	·	·	·	·	·	·	·	·	·	·	·	·	·
16383	1	1	1	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited.

**Table 3. Binary 11-bit Programmable Counter Data Setting**

Divide ratio(N)	N11	N10	N9	N8	N7	N6	N5	N4	N3	N2	N1
3	0	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	0	1	0	0
·	·	·	·	·	·	·	·	·	·	·	·
2047	1	1	1	1	1	1	1	1	1	1	1

Note: Divide ratio less than 3 is prohibited.

**Table 4. Binary 7-bit Swallow Counter Data Setting**

Divide ratio (A)	A7	A6	A5	A4	A3	A2	A1
0	0	0	0	0	0	0	0
1	0	0	0	0	0	0	1
·	·	·	·	·	·	·	·
127	1	1	1	1	1	1	1

**Table 5. Prescaler Data Setting**

SW	Prescaler divide ratio
1	64/65
0	128/129

**Table 6. Charge Pump Current Setting**

CS	Current value
1	±4.0 mA
0	±1.0 mA

**Table 7. LD/fout Output Select Data Setting**

LDS	LD/fout output signal
1	fout signal
0	LD signal

**(2) Relation between the FC Input and Phase Characteristics**

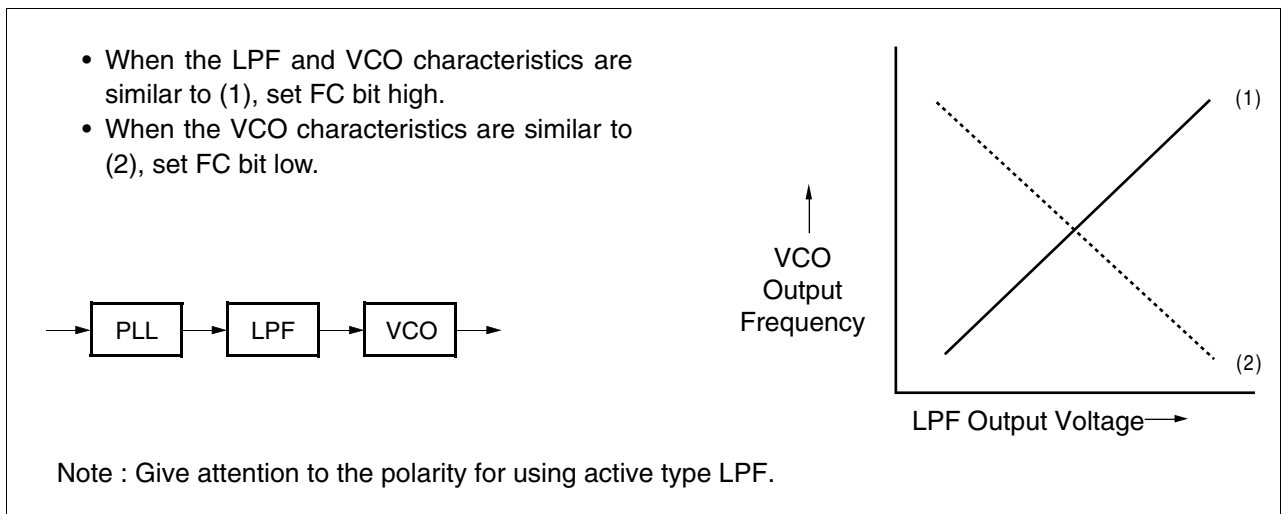
The FC bit changes the phase characteristics of the phase comparator. The internal charge pump output level (Do) is reversed according to the FC bit. Also, the monitor pin (fout) output is controlled by the FC bit. The relationship between the FC bit and Do is shown below.

**Table 8. FC Bit Data Setting (LDS = "1")**

	FC = 1		FC = 0	
	Do	LD/fout	Do	LD/fout
$f_r > f_p$	H	fout = fr	L	fout = fp
$f_r < f_p$	L		H	
$f_r = f_p$	Z*		Z*	

\*: High impedance

When designing a synthesizer, the FC pin setting depends on the VCO and LPF characteristics.



### 3. Power Saving Mode (Intermittent Mode Control Circuit)

**Table 10. PS Pin Setting**

PS pin	Status
H	Normal mode
L	Power saving mode

The intermittent mode control circuit reduces the PLL power consumption.

By setting the PS pin low, the device enters into the power saving mode, reducing the current consumption. See the Electrical Characteristics chart for the specific value.

The phase detector output, Do, becomes high impedance.

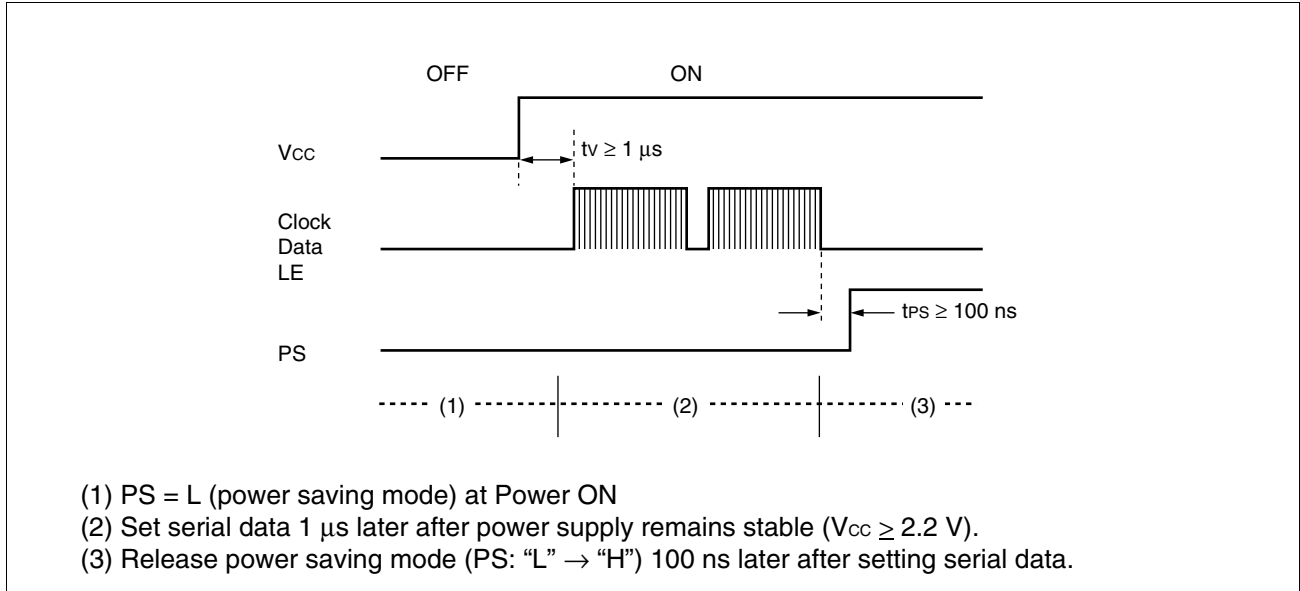
For the signal PLL, the lock detector, LD, remains high, indicating a locked condition.

Setting the PS pin high, releases the power saving mode, and the device works normally.

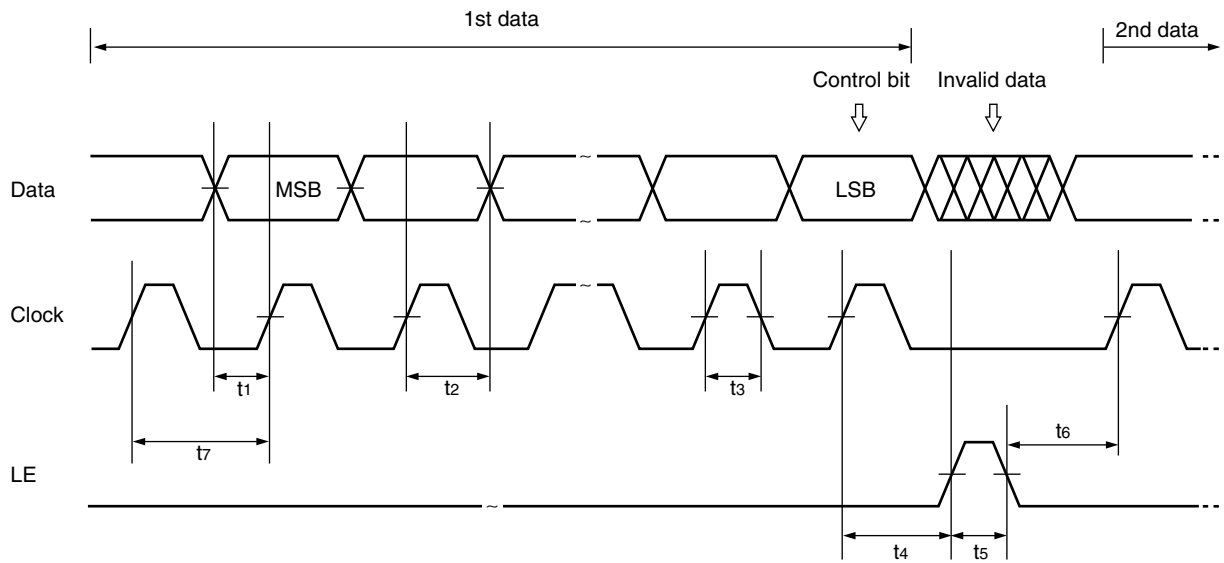
The intermittent mode control circuit also ensures a smooth startup when the device returns to normal operation. When the PLL is returned to normal operation, the phase comparator output signal is unpredictable. This is because of the unknown relationship between the comparison frequency ( $f_p$ ) and the reference frequency ( $f_r$ ) which can cause a major change in the comparator output, resulting in a VCO frequency jump and an increase in lockup time.

To prevent a major VCO frequency jump, the intermittent mode control circuit limits the magnitude of the error signal from the phase detector when it returns to normal operation.

- Notes :
- When power ( $V_{CC}$ ) is first applied, the device must be in standby mode, PS = Low.
  - The serial data input after the power supply becomes stable and the the power saving mode is released after completed the data input..



## ■ SERIAL DATA INPUT TIMING



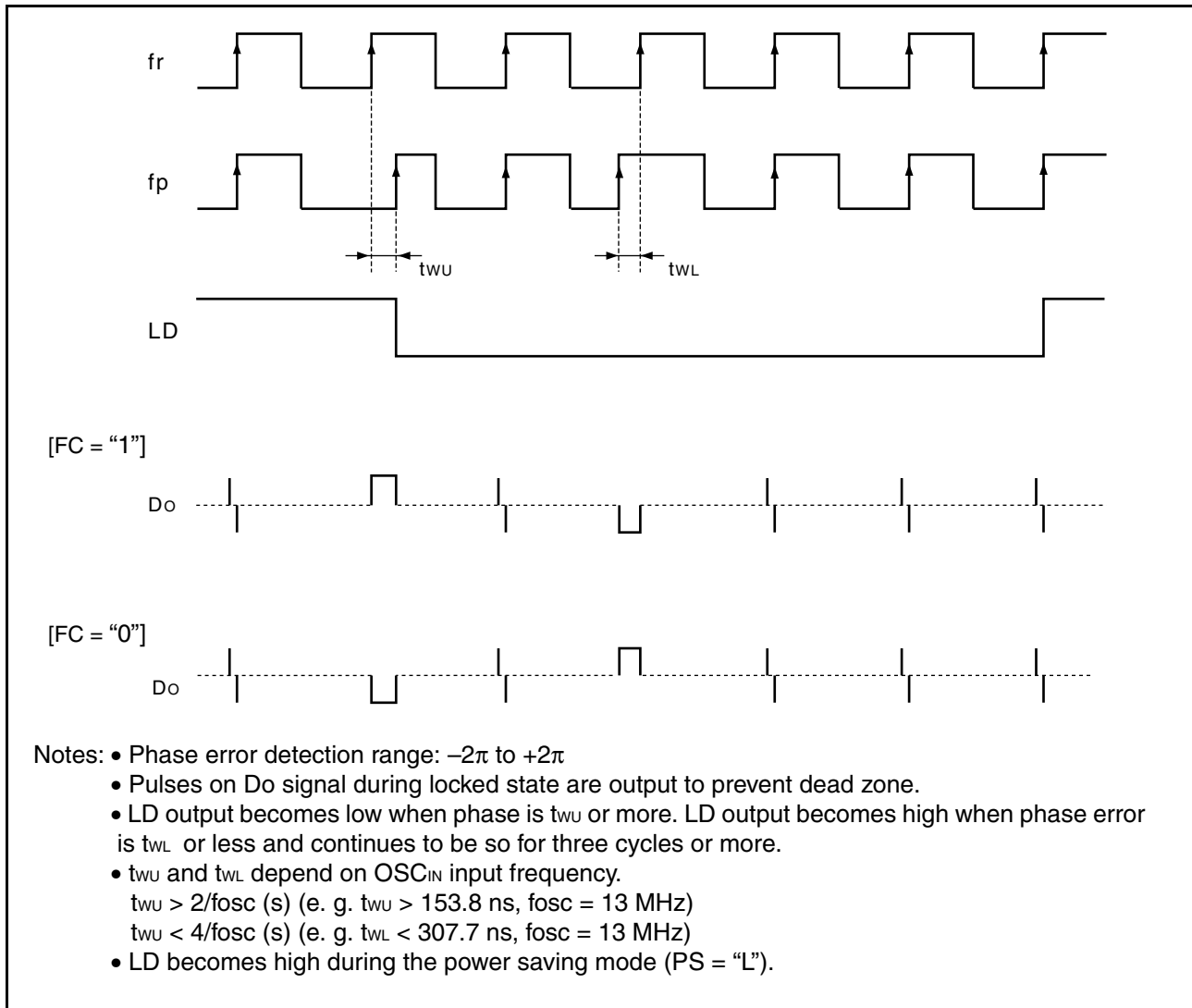
On the rising edge of the clock, one bit of data is transferred into the shift register.

Parameter	Min	Typ	Max	Unit
$t_1$	20	–	–	ns
$t_2$	20	–	–	ns
$t_3$	30	–	–	ns
$t_4$	30	–	–	ns

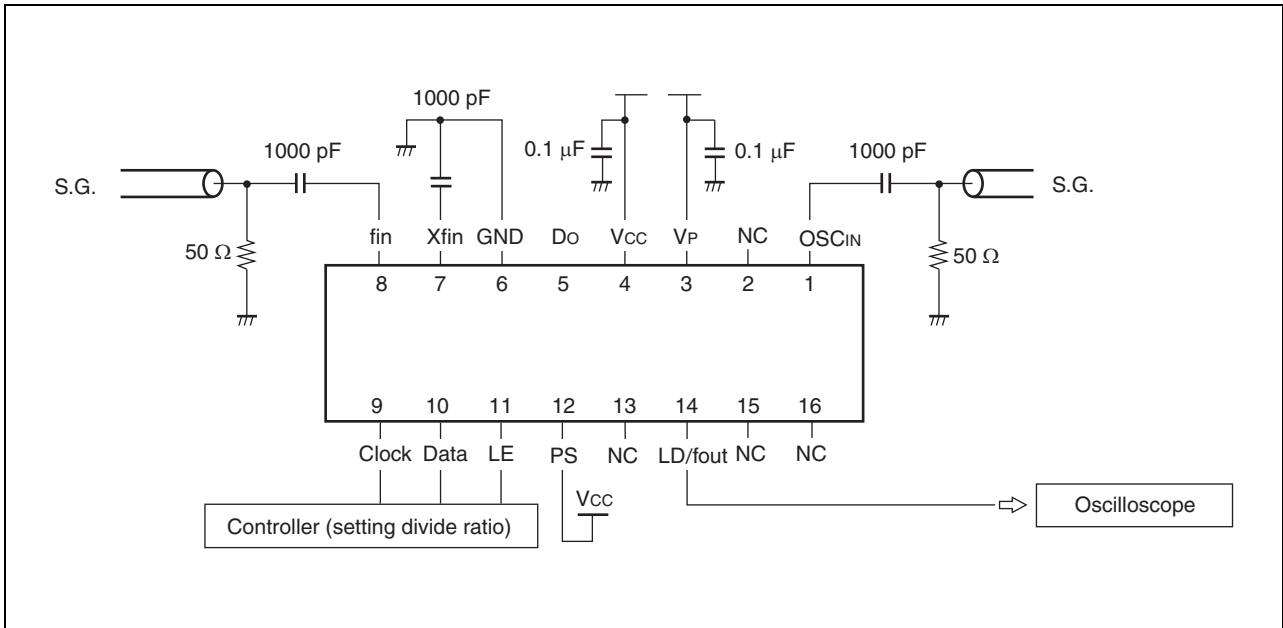
Parameter	Min	Typ	Max	Unit
$t_5$	100	–	–	ns
$t_6$	20	–	–	ns
$t_7$	100	–	–	ns

Note: LE should be “L” when the data is transferred into the shift register.

## ■ PHASE COMPARATOR OUTPUT WAVEFORM

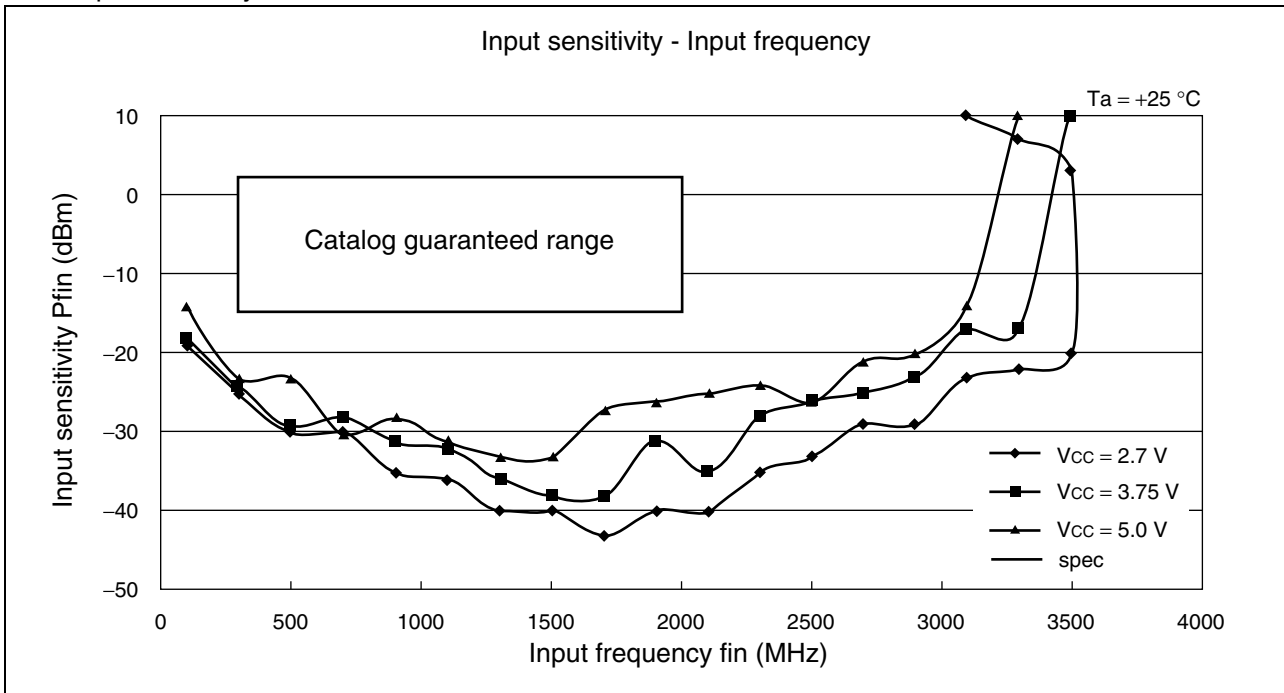


## MEASUREMENT CIRCUIT (for Measuring Input Sensitivity $f_{in}/OSC_{IN}$ )

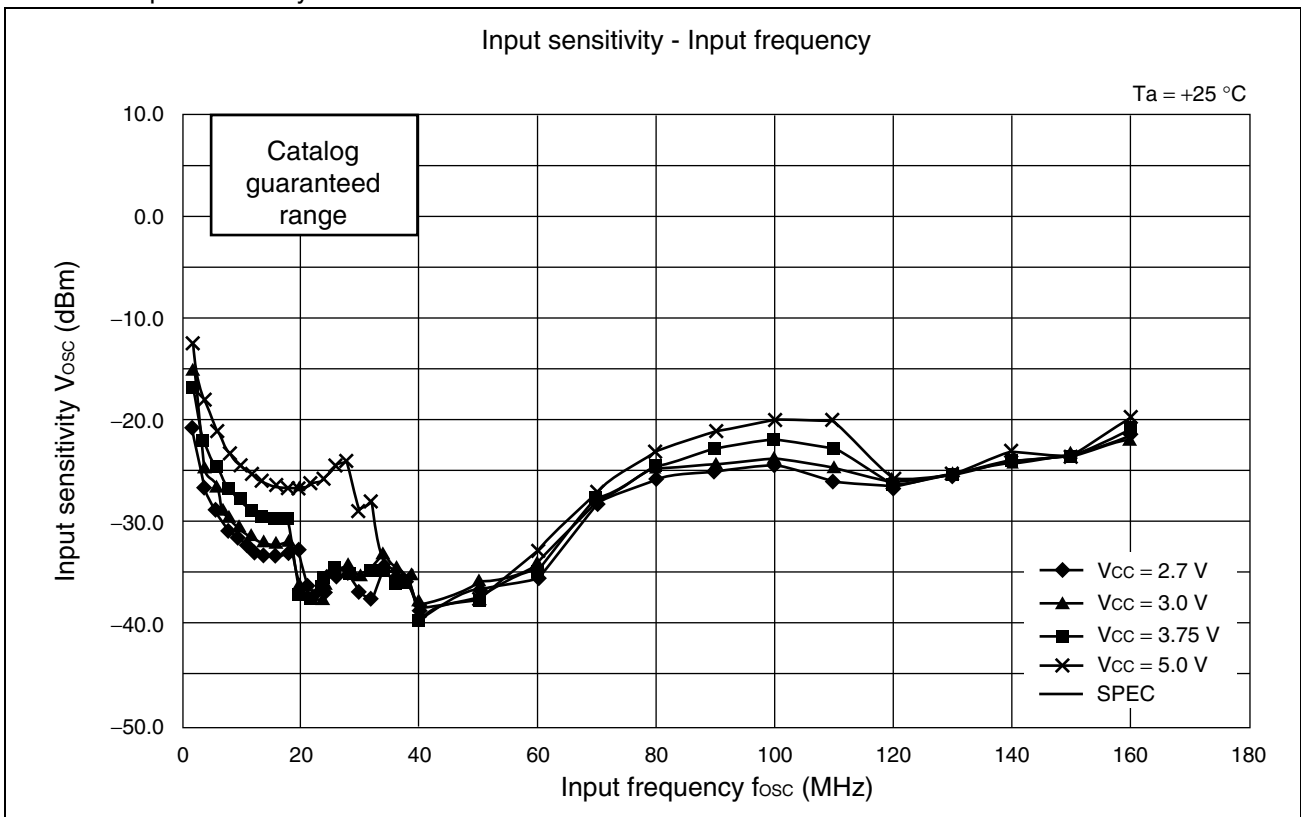


## TYPICAL CHARACTERISTICS

### 1. $f_{in}$ input sensitivity

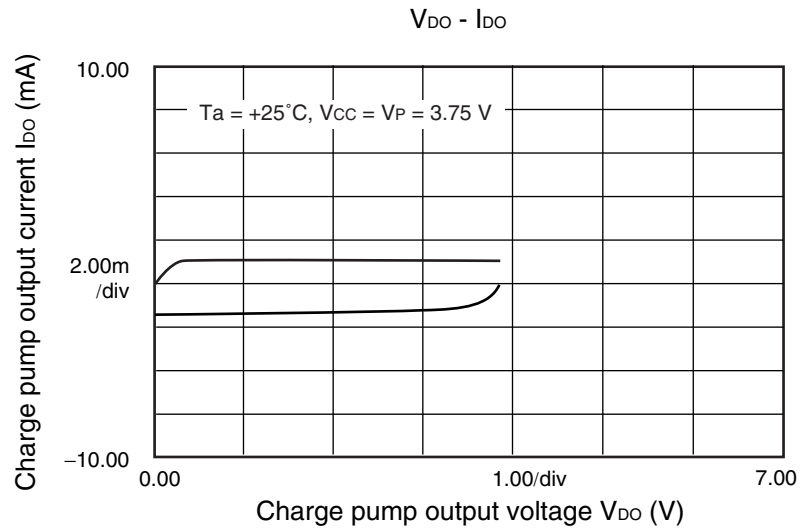


### 2. $OSC_{IN}$ input sensitivity

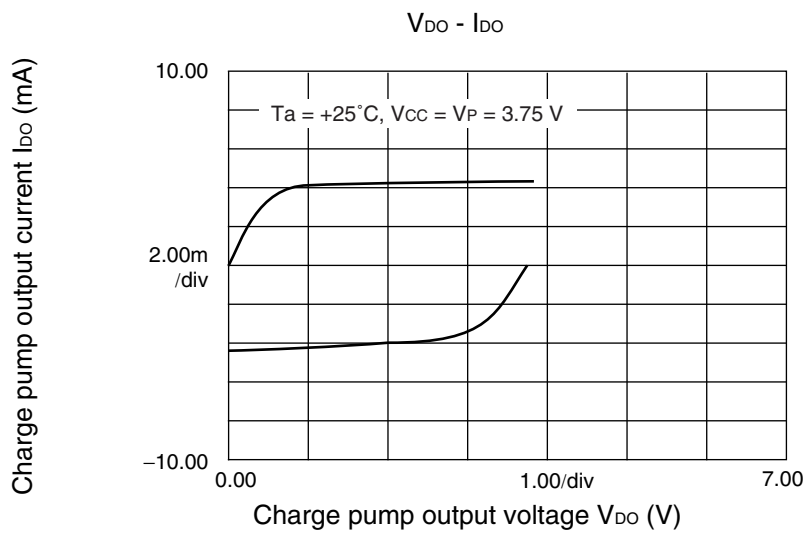


### 3. Do output current

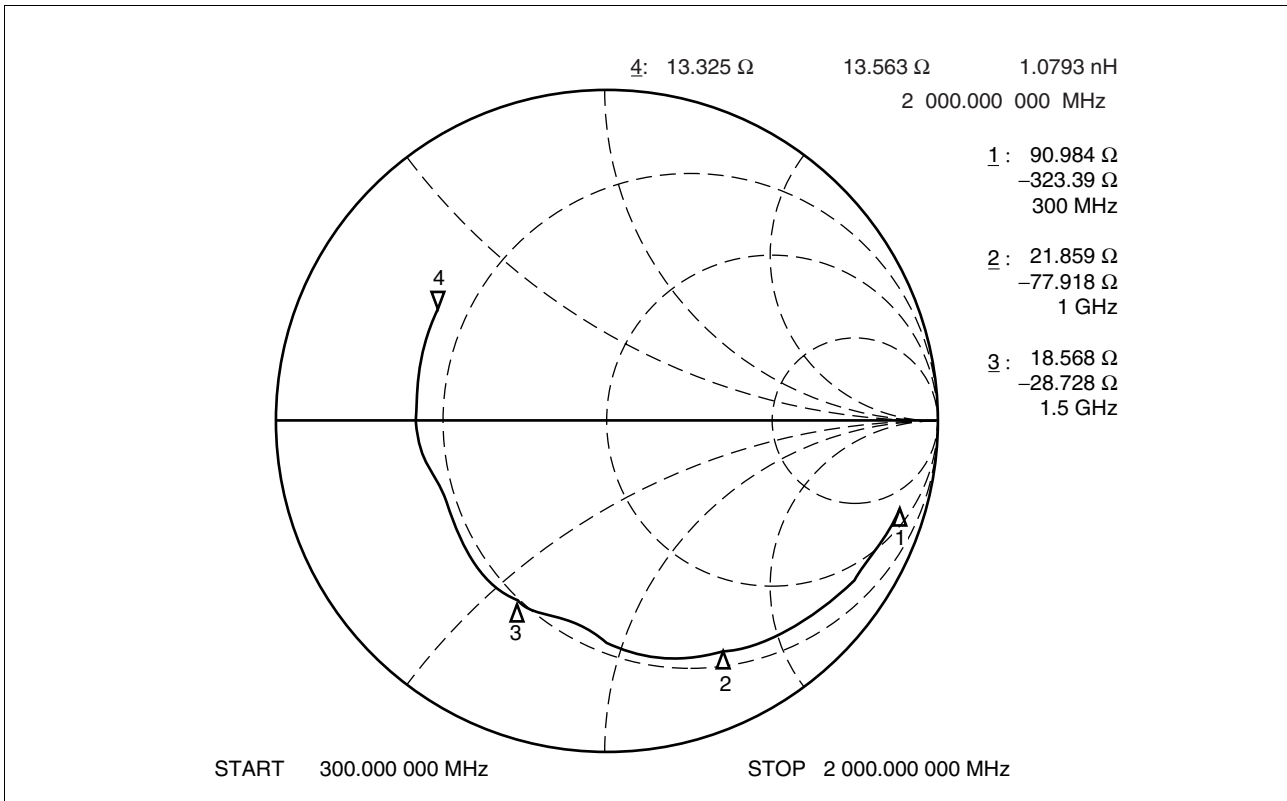
1.0 mA mode



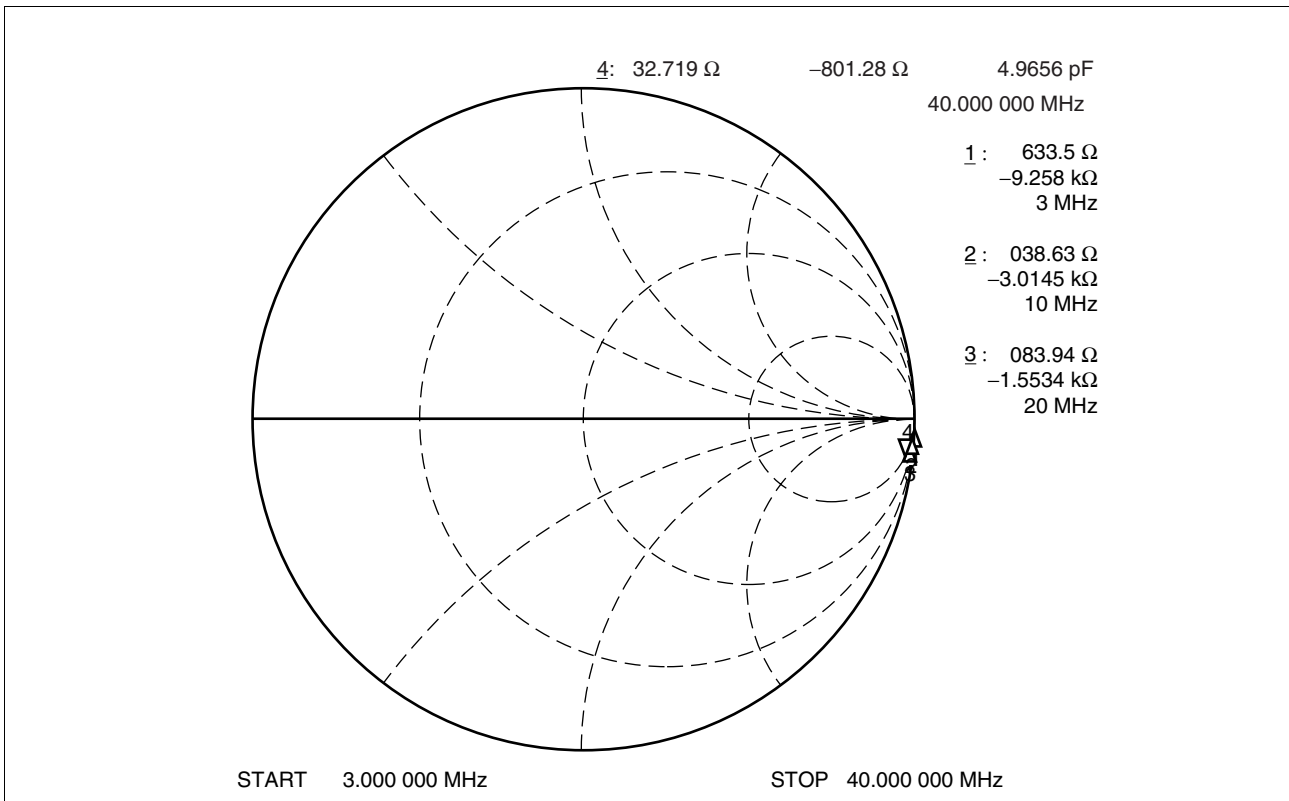
4.0 mA mode



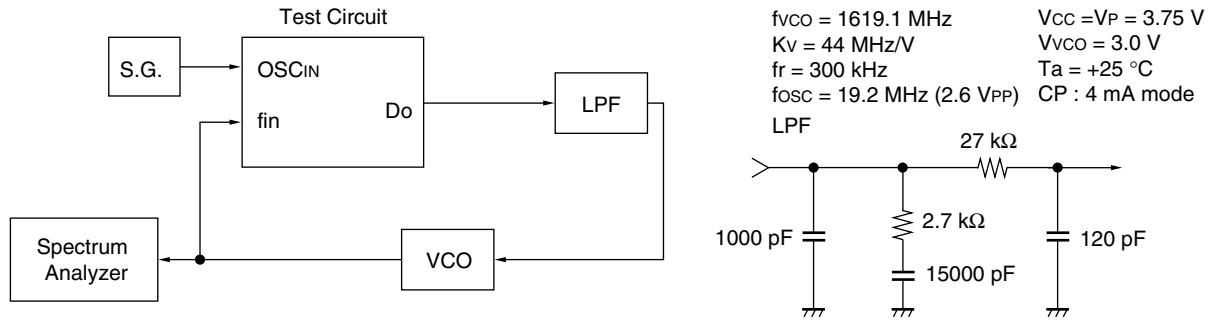
## 4. fin input impedance



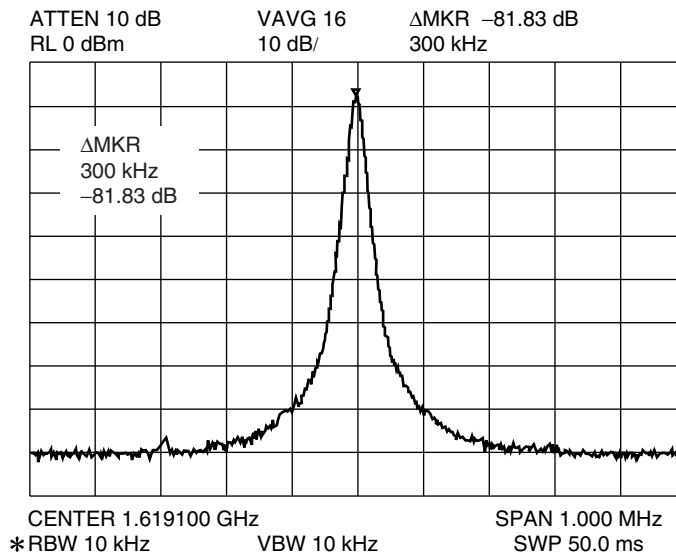
## 5. OSC<sub>IN</sub> input impedance



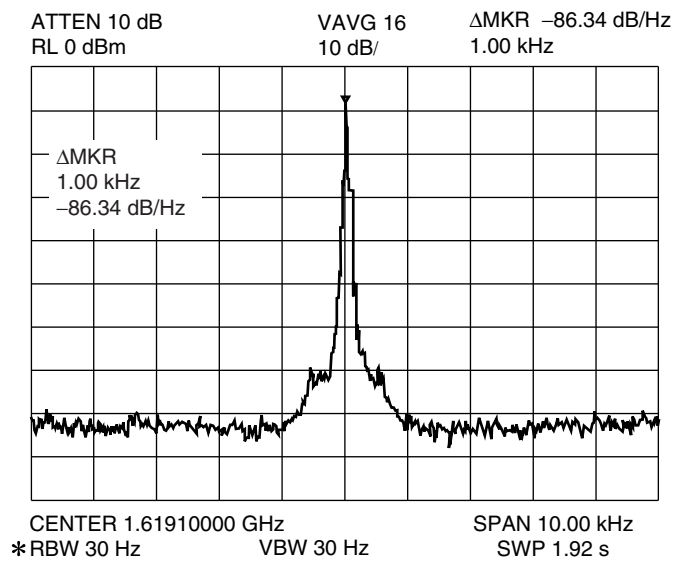
## REFERENCE INFORMATION



### PLL Reference Leakage

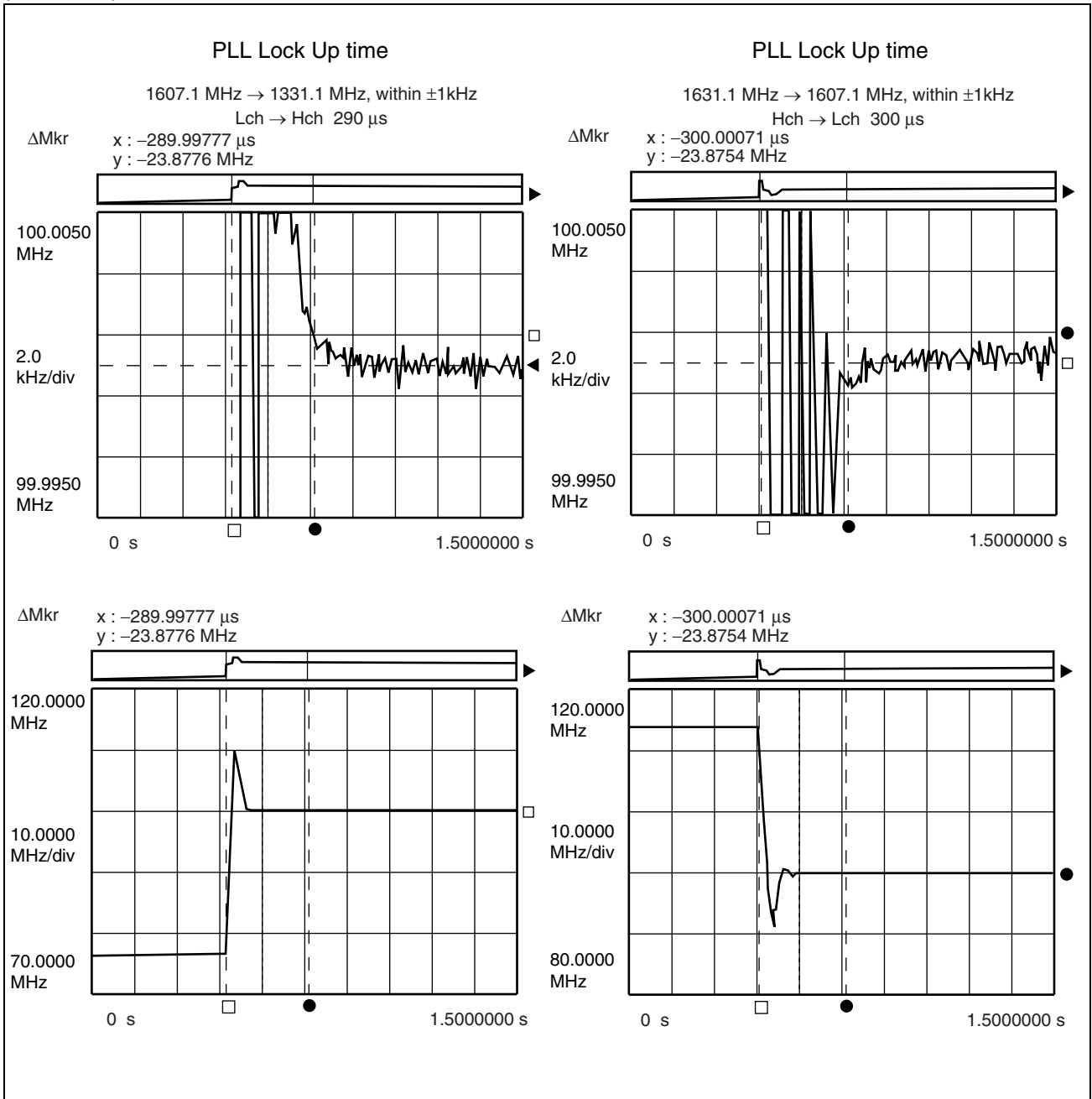


### PLL Phase Noise



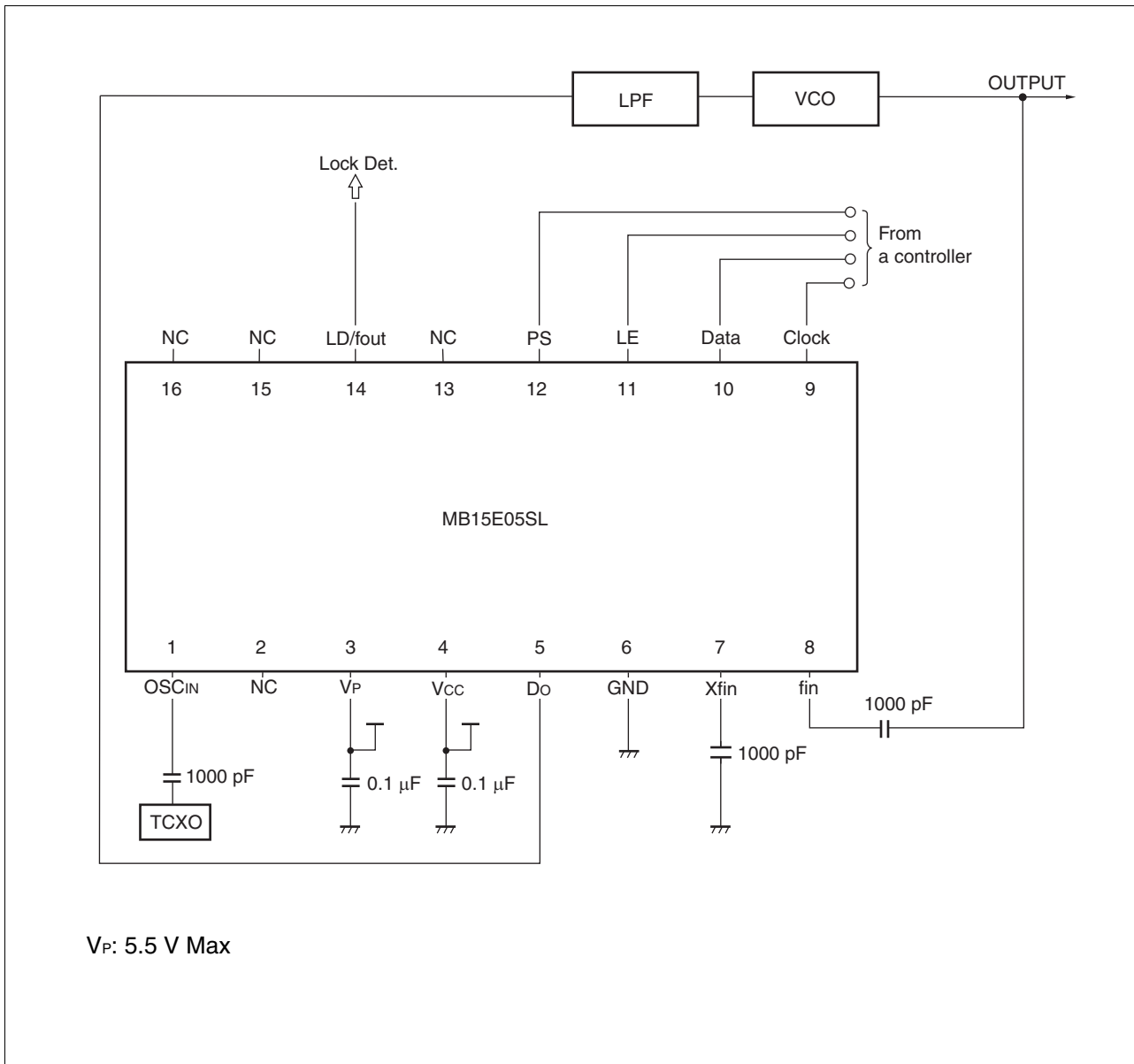
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# MB15E05SR

## ■ APPLICATION EXAMPLE



## ■ USAGE PRECAUTIONS

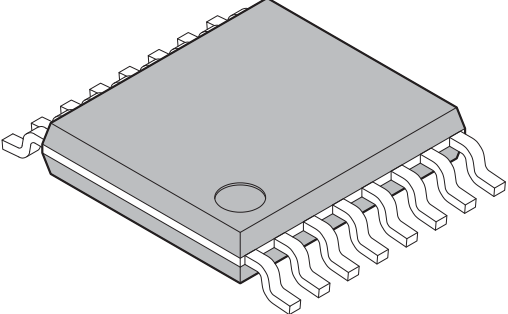
- To protect against damage by electrostatic discharge, note the following handling precautions:
- Store and transport devices in conductive containers.
  - Use properly grounded workstations, tools, and equipment.
  - Turn off power before inserting device into or removing device from a socket.
  - Protect leads with a conductive sheet when transporting a board-mounted device.

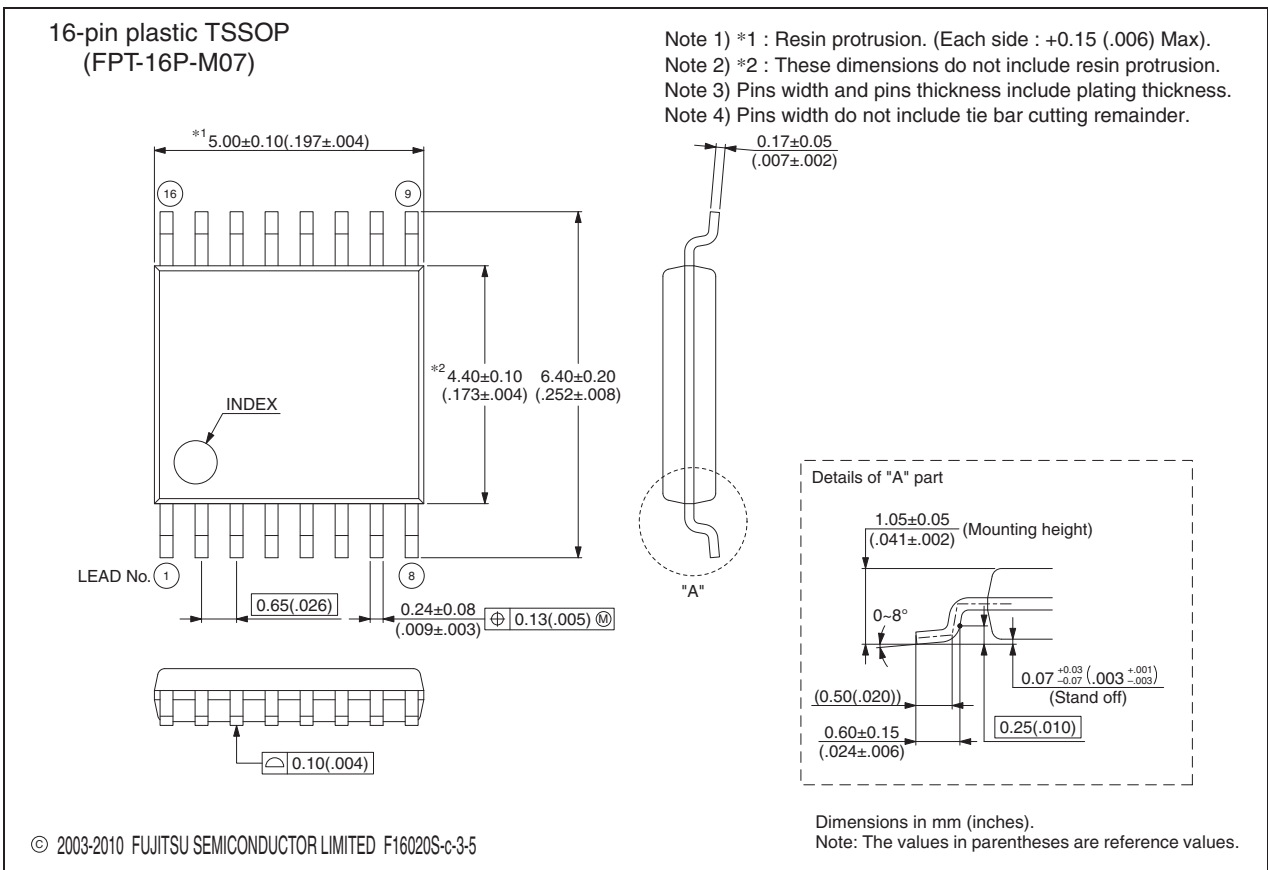
## ■ ORDERING INFORMATION

Part number	Package	Remarks
MB15E05SRPFT	16-pin, Plastic TSSOP (FPT-16P-M07)	

# MB15E05SR

## PACKAGE DIMENSIONS

<p>16-pin plastic TSSOP</p>  <p>(FPT-16P-M07)</p>	Lead pitch	0.65 mm
	Package width × package length	4.40 × 5.00 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.10mm MAX
	Weight	0.06g
	Code (Reference)	P-TSSOP16-4.4×5.0-0.65



**MEMO**

# MB15E05SR

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